

2025.3.5(Wed.) – **3.7**(Fri.) Makuhari Messe

Final Report

Organizers: JAPAN INDUSTRIAL PUBLISHING CO., LTD. Sankei Shimbun Co., Ltd.



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Introduction

Grinding Technology Japan 2025

The 4th Grinding Technology Japan (GTJ) 2025 has come to a successful close. We would like to express our sincere gratitude to all exhibitors.

The number of exhibitors increased significantly this year.

In addition, the number of visitors reached a record high due to the addition of the SiC,GaN Machining Technology Exhibition. We also received many compliments from exhibitors about the quality of visitors.

We will be expanding the show floor over the next two years to provide a more visible and active venue for business discussions.

We look forward to seeing you at Grinding Technology Japan 2027.

SiC, GaN Machining Technology Exhibition 2025

The 1st SiC, GaN Machining Technology Exhibition has closed with great success.

We would like to take this opportunity to express our sincere appreciation for the cooperation of all exhibitors, visitors and many related parties.

Although it was held for the first time, many companies and organizations exhibited their products and services, and the panel discussions and other events were well attended and successful.

We are very pleased that this exhibition has provided you with a valuable experience as a place to showcase the latest technologies and engage in practical discussions.

We will continue our efforts to contribute to the development of the industry.

Society of Japan / Deburring, Surface finishing, Cleaning Association Japan Association Japan

We look forward to seeing you at the next SiC, GaN Machining Technology Exhibition 2027.

JAPAN INDUSTRIAL PUBLISHING CO., LTD., SANKEI SHIMBUN CO., LTD.,

Outline Opening hours 10:00–17:00 Dates March 5 (Wed.) - 7 (Fri.), 2025, 3 days Venue Makuhari Messe Exhibition Hall 8 Entrance Fee Free with pre-registration Organizers JAPAN INDUSTRIAL PUBLISHING CO., LTD. / SANKEI SHIMBUN CO., LTD., Grinding Technology Japan 2025 (GTJ 2025) Title SiC,GaN Machining Technology Exhibition2025 Special cooperation Project by JAPAN INDUSTRIAL PUBLISHING CO., LTD., The Japan Society for Abrasive Technology "Machines and Tools" Editorial Department, The Japan Society for Applied Physics Advanced Power Semiconductors Supporting organizers Embassy of the Federal Republic of Germany in Japan **Cooperate Organizations** Special Partner Sessaku Forum 21 Japan Precision Machine Association / Japan Forming Machinery Association / Japan Machine Tool Distributors Association / Japan Machine Tool Importers' Special cooperation The Japan Society for Abrasive Technology Association / The Japan Machine Tool Builders' Association / Japan Cutting & Network partner Grind Tec Wear-resistant Tool Association / JAPAN OPTICAL MEASURING INSTRUMENTS MANUFACTURERS' ASSOCIATION / The Japan Machine Accessory Association / Cooperate Organizations the Japan Fluid Power System Society / Japan Precision Measuring Instruments Manufacturers Association / Japan Grinding Wheel Association / Industrial Japan Machine Tool Builders' Association / Japan Machine Tool Importers' Association Diamond Association of Japan / Japan Fluid Power Association / Japan Gear / Japan Machine Tool Distributors Association / Japan Forming Machinery Association / Manufacturers Association / The Japan Society for Precision Engineering / Japan Precision Machine Association / The Japan Cutting & Wear-resistant Tool Association Turbomachinery Society of Japan / Japan Saw blade & Knife Industrial Association / Japan Machine Accessory Association / Japan Precision Measuring Instruments / SiC Alliance / Consortium for GaN Research and Applications Manufacturers Association / Japan Grinding Wheel Association / Industrial Diamond Association of Japan / Japan Optical Measuring Instruments Manufacturers' Association / Japan Fluid Power Association / Japan Gear Manufacturers Association / Japan Testing Machine Association / Japan Knife Sharpening Association / Japan Saw blade & Knife Industrial Association / Japan Machine Saw and Knife Industry Association / The Japan Society for Precision Engineering / Japan Fluid Power System Society / Turbomachinery Machining





■Exhibition Scale

	2025			2023	
	Number of exhibitors / booths	249 companies, organizations and laboratories	320 booths	171 companies, organizations and 294 laboratories	
Break	Grinding Technology Japan2025 Exhibitors	126 companies/organizations	264 booths	113 companies/organizations	
down	SiC,GaN Machining Technology Exhibition2025 Exhibitors	53 companies/organizations	56 booths	_	
The Japa	an society for Abrasive Technology, Research Presentation Corner	24 laboratories		22 laboratories	
The Japa	n society for Abrasive Technology, Graduation Research Presentation	29 laboratories		23 laboratories	
The Japa	an society for Abrasive Technology, Supporting Member Corner	17 companies		13 companies	

■ Products exhibited: Grinding Technology Japan 2025 Grinding machines, Polishing machines, Grinding wheels, Truing machines, Precision measuring devices, Peripheral devices, Tool Grinding machines, Cutting tools, Cutting tools processing technologies, Cutting tools applicated technologies, Cutting oil, Cutting oil supply devices, Cutting oil filters, Materials, etc.

> SiC, GaN Machining Technology Exhibition 2025 SiC, GaN Ingot Slicing Machine, SiC, GaN Wafer Grinding Machine, SiC, GaN Grinding Stones, Wafer Beveling Machine, SiC, GaN Single / Double-Side Lapping Machine, SiC, GaN Chemical, Mechanical Polishing Machine, CMP Slurries for SiC,GaN,Wafer Cleaning System, Wafer Shape Measuring Machine, etc

■Number of visitors

Day	2023	Weather	Grinding Technology Japan 2025
March 5 (Wed)	1,786	Rain	1,426
March 6 (Thu)	2,074	Cloud	1,549
March 7 (Fri)	2,664	Fine	1,810
Total	6,524	-	4,785

Number of visitor who registered at the reception desk Visitors who attend the exhibition over multiple days during the event have been counted as one visitor.

Reception Party

Date March 5, 2025 (Wed) 17:30 - 19:00

Venue

International Conference Room International Conference Hall, Makuhari Messe

[Program]

1. Greeting from the Organizer

•Mr. Hiroshi Oyama Editor-in-Chief, Machine.and. Tool, .. JAPAN. INDUSTRIAL. PUBLISHING. CO... LTD.

•Mr. Kenji Kawata, Ph.D Supervisor, JAPAN.INDUSTRIAL. PUBLISHING.CO.,.LTD.

2. Congratulatory Address by Guest of Honor

•Mr. Daisuke Shimizu President, The Japan Society for Abrasive Technology • Dr. Oshima Takeshi Chair of Committee. The Japan Society of Applied Physics Advanced Power Semiconductors Division

3.Kagami Biraki

• Mr. Tsukuru Takai Chairman, Cutting Forum 21

• Dr.Eng. Shinji Shimizu Director Museum of Industrial Technology NIPPON INSTITUTE OF TECHNOLOGY

• Mr. Daisuke Shimizu President, The Japan Society for Abrasive Technology

Chair of Committee, The Japan Society of Applied Physics Advanced Power • Dr. Oshima Takeshi

Semiconductors Division

• Dr.Eng. Tomohisa Kato Wafer Process Team Leader, Senior Research Scientist,

Advanced Power Electronics Research Center

• Dr. Claus Itterheim Delegierter der Fordermitglieder, FDPW (President, ISBE GmbH)

•Mr. Hiroshi Oyama Editor-in-Chief, Machine.and. Tool, .. JAPAN. INDUSTRIAL. PUBLISHING. CO., .LTD.

Mr. Kenji Kawata,Ph.D Supervisor, JAPAN.INDUSTRIAL. PUBLISHING.CO.,.LTD. •Mr. Ryuichi Kawai Director, Expo Planning Division, Sankei Shimbun Co., Ltd.

4 Toast

• Mr. Tsukuru Takai Chairman, Cutting Forum 21

4. Closing Remarks

• Mr. Ryuichi Kawai Director, Expo Planning Division, Sankei Shimbun Co., Ltd.





















Grinding Technology Japan 2025 Exhibitor List

Exhibitor Name / Co - exhibitor Name	Booth No.
A.L.M.T. Corp.	G-094
AFC Japan Corporation	G-004
/ Hyperion Materials & Technologies Japan	G-004
ALTEX CO., LTD.	G-083
AMADA MACHINERY CO., LTD.	G-056
AREUSE Co., Ltd.	
/ HORKOS Corporation	G-038
/ IWASHITA INDUSTRIAL Co., Ltd.	
Asahi Diamond Industrial Co., Ltd.	G-042
Asahi Sho-ko-sha Co., Ltd.	G-006
Association Deburring Surface finishing and Cleaning	G-087
Brinkmann Pumps Japan Co., Ltd.	G-062
BUNRI Inc.	G-032
CemeCon K.K.	G-054
COOL TECH LTD.	G-099
CR GEMS Superabrasives Co., Ltd.	G-014
Daiya Seiki Co., Ltd.	G-093
DENGFENG WUDU ABRASIVES CO., LTD.	G-020
Dynamic Tools Corporation	G-100
EHWA DIAMOND CO., LTD.	G-030
EISEN CO., LTD.	
/ RESMOTOOL CO., LTD.	G-005
/ SION DIAMOND Co., Ltd.	
Foshan Huagao Abrasive Co.,Ltd	G-012
Fukuda Corporation	G-064
FUTAMURA MACHINES & TOOLS CO., LTD.	G-060
GLOBAL DIAMOND CO., LTD.	G-082
Gosho Co., Ltd.	G-059
HAMAI CO., LTD.	G-095
HENAN ABRASIVESTOCKS TECHNOLOGY CO.,LTD	G-016
Henan Boreas New Material Co.,Ltd	G-108
Henan HengXin Industrial&Mineral Products Co.,Ltd.	G-106
Henan Hold Diamond Technology Co., Ltd	G-104
HENAN KEMEI ABRASIVES CO.,LTD.	G-018
Henan Ruiheng New Material Co., Ltd.	G-097
Henan Sanhui New Materials Co.,Ltd	G-096
Henan SEPPE TECHNOLOGIES CO., LTD	G-105
Henan Yuxing Carbon Material Co., Ltd	G-009
IRINOKIKO Co., Ltd.	G-040
ISBE GmbH	
/ FDPW	G-035
ISHIKAWA Tool Grind Co., Ltd.	G-028

IZUMI SANGYO CO., LTD.	G-088 G-002
JAPAN RIHON CO., LTD.	G-052
	G-089
JTEKT CORPORATION	
	G-101
/ JTEKT GRINDING TOOLS CORPORATION /MITSUI SEIKI KOGYO CO., LTD.	
KATAGIRI SEISAKUSHO CO., LTD ; INC.	G-068
	G-080
KIRA CORPORATION C	G-045
KIRISHIMA CO., LTD.	G-055
	G-029
KOIZUMI TOOL CO., LTD.	G-046
	G-109
Lubrication Technology Inc.	G-072
	G-008
Makino Seiki Co., Ltd.	G-027
Meister Incorporated (G-022
MISUZU CO., LTD.	G-098
Mitsuikokuin Co., Ltd.	G-069
Monodukuri Review	G-074
	G-075
Nagel Aoba Precision Co., Ltd.	G-081
/ ELGAN Diamantwerkzeuge GmbH & Co. KG	G-001
	G-047
NIKKO CASTY CO., LTD.	G-039
/ Kansai Tokusyu Kosaku-yu Co., Ltd.	G-039
	G-044
	G-076
	G-066
	G-053
	G-003
Okamoto Machine Tool Works, Ltd.	G-102
	G-043
	G-086
	G-067
	G-050
RYOCO SEIKI CO., LTD.	G-036
S&F Inc.	G-001
/ SAV GMbH	G-001
	G-079
SANWA CREATION Co., Ltd.	G-031

Exhibitor Name / Co - exhibitor Name	Booth No.
Seiko Instruments Inc.	G-034
Sessaku Forum21	G-023
Shanxi Taiyue Abrasive co.,ltd.	G-013
SHIGIYA MACHINERY WORKS LTD.	G-033
SIGMA ELECTRONICS CO., LTD.	G-071
Sohryu Sangyo Co., Ltd.	G-084
SUGINO MACHINE LIMITED	G-049
Sumitomo Heavy Industries Finetech, Ltd.	G-025
TAIYO KOKI CO., LTD.	G-041
Taiyu Japan	G-077
THE SPACE BUSINESS NEWS LLC	G-073
Three-F Giken Co., Ltd.	G-070
Tokaloy Co., Ltd.	G-037
TOKUPI CO., Ltd.	G-085
TOKYO DIAMOND TOOLS MFG Co., LTD.	G-063
TOKYO SEIMITSU CO., LTD.	G-090
TOMEI DIAMOND Co., Ltd.	G-091
Tosho Shoji Co., Ltd.	G-078
TOYO KENMAZAI KOGYO LTD.	G-051
Transor Filter Japan Co., Ltd.	G-065
Tyrolit Japan KK	G-057
UNIMAGTECH KK.	G-048
UTSUNOMIYA SEISAKUSHO CO., LTD.	G-058
Vollmer Japan Corp.	G-024
XUCHANG GREAT ABRASIVE CO.,LTD.	G-017
YAMASHITA WORKS CO,.LTD	G-092
/ Japan Speed Shore Co., LTD.	G-092
YUASA TRADING CO., LTD.	
/ TSUGAMI CO., LTD.	
/ SUN MAINTENANCE KOKI CO.,LTD.	G-061
/ JCC Co.,Ltd	
/ Toyo Screen Kogyo Co., Ltd.	
ZHENG ZHOU SILICA NEWMATERIALCO.,LTD	G-010
ZHENGZHOU HEYDAY ABRASIVES CO., LTD	G-007
ZHENGZHOU JIADING ABRASIVE MANUFACTURING CO., LTD	G-019
Zhengzhou Ruizuan Diamond Tool Co., Ltd	G-021
ZHENGZHOU XIANGYU NEW MATERIAL CO., LTD.	G-107
Zhengzhou Xinli Wear-Resistant Material Co., Ltd.	G-103
Zhengzhou ZZDM SUPERABRASIVES CO.,LTD	G-011
ZOLLER Japan K.K.	G-026

The Japan Society for Abrasive Technology Supporting Member Corner

ADAMAS
Asahi Diamond Industrial Co.,Ltd.
CHUO PRECISION INDUSTRIAL CO.,LTD.
Fuji Die Co., Ltd.
Hyperion Materials & Technologies
JTEKT GRINDING TOOLS CORPORATION

MACOHO Co., Ltd.
Makino Seiki Co.,Ltd.
MICRON MACHINERY CO., LTD.
MIZUHO Co.,Ltd.
MOLDINO Tool Engineering, Ltd.
Nakamura-Tome Precision Industry Co., Ltd.

Nippon Tungsten Co.,Ltd.	
NORITAKE CO.,LIMITED	
Okuma Corporation	
SINTOKOGIO, LTD.	
ULTRASONCTOOLNG LABORATORY	_

The Japan Society for Abrasive Technology Research Presentation Corner

Advanced Manufacturing Research Centre, Shibaura Institute of Technology
Akita prefectural university
Ashikaga University
Chubu University
Chubu University
Department of Mechanical Engineering, Chiba University
Division of Mechanical Science and Technology Graduate School Science and Technology Gunma University

Iwate University, Water Machining Environmentally Friendly
System Network (Water Machining System Network)

Kansai University
Manufacture Development Innovation Center, Chubu University
Matsui Laboratory, Chiba Institute of Technology
Micro and Nano Engineering Laboratory (HASE Laboratory),
Saitama Institute of Technology
Nakao Laboratory, Kanagawa University
Nano-Engineering Laboratory (Shimizu-Onuki-Ojima Lab.),
Ibaraki University
National Defence Academy of Japan
National Defence Academy of Laboratory Academy of School Papanetics of Technology, National Defence Academy of

National Defence Academy of Japan
National Institute of Technology, Sasebo College Dept. of
Control Engineering
Nippon Institute of Technology
Nippon Institute of Technology, Ninomiya Lab.
Okayama University
Ritsumeikan University
Sano Laboratory, The University of Osaka
Science of Production and Environment Laboratory,
Saitama University

Surface Engineering and Manufacturing Laboratory,
Tokyo City University
Suwabe Laboratory, Kanazawa Institute of Technology
Tohoku University
Tokyo Denki University
Toyama Prefectural University, IWAI Laboratory
Yamada & Uchida Laboratory, Nihon University
Yamamura Laboratory, The University of Osaka

SiC,GaN Machining Technology Exhibition 2025 Exhibitor List

Exhibitor Name / Co - exhibitor Name	Booth No.
A.L.M.T. Corp.	S-10
Aamilia Japan, Inc.,	S-51
Aixtal Corporation	S-28
BAIKOWSKI JAPAN CO., LTD.	S-45
Brimatec, LLC	S-29
Ceramic Forum Co., Ltd.	S-49
EBARA CORPORATION	S-15
ENGIS JAPAN CORPORATION	S-17
Fujikoshi Machinery Corp.	S-37
FUJIMI INCORPORATED	S-43
Guangzhou Summit Crystal Semiconductor Co.,Ltd	S-08
HAMAI CO., LTD.	S-09
Huai'an Litai Silicon Carbide Micro Powder Co., Ltd	S-01
Insight k.k.	S-46
JFE Techno-Research Corporation	S-33
JTEC CORPORATION	S-20
JTEKT MACHINE SYSTEMS CORPORATION	S-47

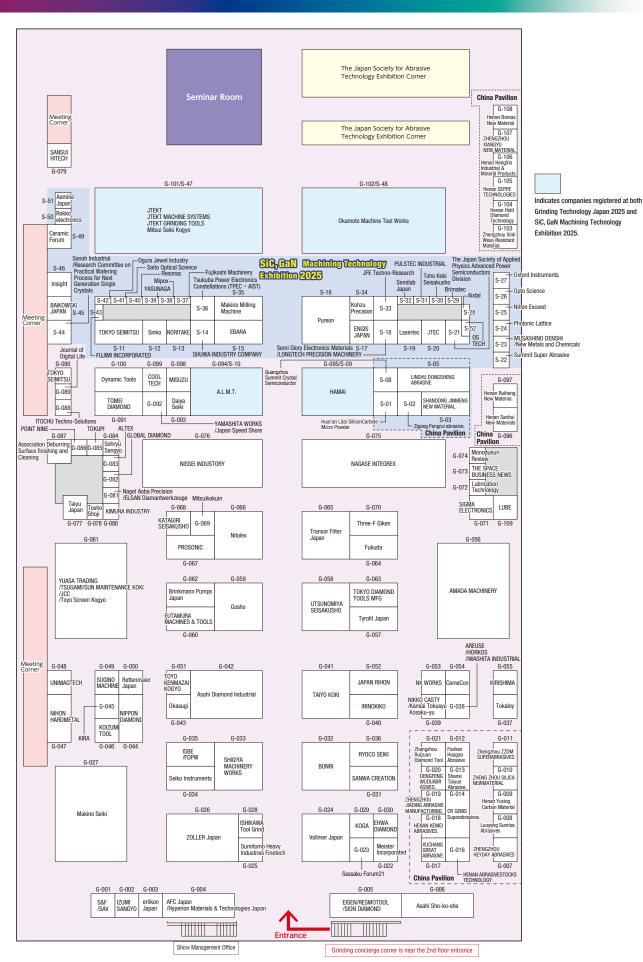
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Kohzu Precision Co., Ltd.	S-34
Lasertec Corporation	S-19
LINSHU DONGSHENG ABRASIVE CO,LTD	S-05
Makino Milling Machine Co., Ltd.	S-35
Mipox Corporation	S-38
MUSASHINO DENSHI, INC.	S-23
/ New Metals and Chemicals Corporation, Ltd.	3-23
Nihon Exceed Corporation	S-25
NORITAKE CO., LIMITED	S-13
Ogura Jewel Industry Co., Ltd.	S-42
Okamoto Machine Tool Works, Ltd.	S-48
Opto Science, Inc.	S-26
OS TECH CO.,LTD.	S-52
Oxford Instruments KK	S-27
Photonic Lattice, Inc.	S-24
PULSTEC INDUSTRIAL CO., LTD.	S-31
Pureon Ltd.	S-16
Resonac Corporation	S-40
Resonac Corporation	S-40

Exhibitor Name / Co - exhibitor Name	Booth No.
Rokko electronics Co., Ltd.	S-50
Saito Optical Science Co., Ltd.	S-41
Sanoh Industrial Co., Ltd.	S-44
/ Research Committee on Practical Wafering Process for Next Generation Single Crystals	5-44
Semi Glory Electronics Materials Co., Ltd.	S-18
/ LONGTECH PRECISION MACHINERY CO., LTD.	5-10
Semilab Japan KK	S-32
SHANDONG JINMENG NEW MATERIAL CO., LTD.	S-03
SHUWA INDUSTRY COMPANY LIMITED	S-14
Sinko Co., Ltd.	S-12
Summit Super Abrasive Co., Ltd.	S-22
The Japan Society of Applied Physics Advanced Power Semiconductors Division	S-21
Toho Koki Seisakusho Co., Ltd.	S-30
TOKYO SEIMITSU CO., LTD.	S-11
Tsukuba Power Electronics Constellations(TPEC · AIST)	S-36
YASUNAGA CORPORATION	S-39
Zigong Fengrui abrasive Co.,Ltd.	S-02





Floor Plan







Event

GTJ Panel Discussion

March 5th

5-K1 10:30-12:00 Thinking about the future of tool making and tool grinding: DX-ization and Automation".

Cordinator: Dr.Eng. Shinji Shimizu / Director Museum of Industrial Technology NIPPON INSTITUTE OF TECHNOLOGY

: Mr. Ryosuke Sato / General Manager, Maintenance Group General / Manager, Manufacturing Technology Depy MOLDINO Tool Engineering, Ltd.

Mr. Teiji Anzai / Executive Director General Manager Engineering Department MAKINO SEIKI CO.,LTD

Mr. Carl Moser / President & Representative Director VOLLMER JAPAN CORP.

Mr.Toru Okura / Technical Manager Tool Grinding Application United Grinding Japan K.K.









GTJ Keynote Speach

March 7th

7-K1 10:30–11:15

Niche Top Strategies and Industry-Academia Collaboration for Japanese Machine Tool Manufacturers

Most of Japan's machine tool manufacturers are so-called "small and medium-sized companies," but they possess superior products and technologies in specific fields and

have existed for many years as an indispensable presence for their customers and their machining processes.

However, in recent years, the environment of small and medium-sized machine tool manufacturers has become increasingly severe due to the intensifying competition from emerging manufacturers and the globalization of the market, the emergence of new technologies in the software field represented by Al. etc., and the ultra-high precision requirements. In this talk, I would like to propose a niche-top strategy as a means to survive in such an era, while discussing how industry-academia cooperation should work.

Mr. Daisuke Shimizu / President The Japan Society for Abrasive Technology, President MAKINO SEIKI CO., LTD



GTJ Technical Seminars

March 5th Grinding process

5-S1 13:00–13:45

Prediction and visualization technology for processing results using sensors

Mr. Takeshi Itatsu

Director Executive Technical Director Deputy of Manufacturing Dept. NAGASE INTEGREX CO.,LTD



5-S2 14:00–14:45

Burn depth estimation technology through in-machine grinding burn evaluation system

Mr. Nanki Goto

Assistant Mangager Analysis Technology Sect. Data Analytics R&D Dept.
JTEKT CORPORATION



5-S3 15:00–15:45

Recent trends in flute grinding wheels

Mr. Naoki Uekukida

Chief Application Engineering Dept. Asahi Diamond Industrial Co., Ltd



March 6th Cutting Tools

6-S1 13:00–13:45

How to advance tooling and cutting technology in the age of automation and information technology

Dr. Toshitaka Matsuoka

MATSUOKA Engineering Consultants Office Ltd.



6-S2 14:00–14:45

How will Digital Transformation (DX) change the tools?

Mr. Fumihisa Kono

Manager Strategic Relations /

Machine Tool Solutions Sales Area South and East Asia SANDVIK K.K. COROMANT COMPANY



6-S3 15:00–15:45

The latest tool grinding technology required to produce high value cutting tools

Mr. Fumiharu Nakamura Assistant Manager Sales Dept GOSHO Co.,LTD



March 7th FGS (Flexible Grinding System) opens up a new world of grinding

7-\$1 14:00–14:45

Automated grinding process system for machine tool spindles

Mr. Katsuyoshi Kobayashi

Deputy General Manager Production Engineering Dept. CITIZEN MACHINERY CO..LTD



7-S2 15:00–15:45

Automation Initiatives with Grinding Specification Machines

Mr. Toshiya Honda

Aerospace Group Material Engineering Department Customer Application Center
MAKINO MILLING MACHINE CO..LTD



7-S3 16:00–16:45

Introduction of a realistic Automatic Tool Production (ATP) system by linking a tool grinding machine and a tool measuring machine

Mr.Toru Okura

Technical Manager Tool Grinding Application United Grinding Japan K.K.







Event

SiC, GaN Panel Discussion

March 6th

6-K1 10:30-12:00 Processing Technology of Large Diameter SiC Wafers for Power Semiconductors - Where is the 8-inch Mass Production Process?

Cordinator : **Dr.Eng. Tomohisa Kato** / Wafer Process Team Leader Senior Research Scientist Advanced Power Electronics Research Center
National Institute of Advanced Industrial Science and Technology

Panelist : Mr. Masato Ito, Ph.D / Engineer Leader Production & Technology Development Group-2 Ichihara Production & Technology Center Resonac Corporation

Mr.Kozo Abe / Technical Consultant Neue Techno Labo

Mr. Kenji Igarashi / Manager Product Sales Team HRG Team Leader Application Center TOKYO SEIMITSU CO.,LTD.

Mr. Shinichiro Takami / Manager Semiconductor New Business R&D Section Silicon R&D Dept. FUJIMI INCORPORATED













Concurrently Holding

The Japan Society for Abrasive Technology, Advanced Technology Fair (ATF2025) The Japan Society for Abrasive Technology Exhibition Corner

The Japan Society for Abrasive Technology was founded in 1957 by the Abrasive Grain Processing Society of Japan and the Kansai Abrasive Grain Processing Society of Japan, and became a corporation in 1995. And in 2009, we were recognized as a public interest incorporated association. During this period, we have consistently developed as a society that comprehensively covers practical manufacturing technologies such as abrasive grain processing technology, tool technology, machining machinery, and measurement technology, and as a society that is "useful" and "fun" to participate in.



This year's event featured exhibits from laboratories in a wide range of fields, including the latest grinding technology, grinding tool measurement and evaluation technology, laser processing technology, ultra-precision and micro-machining technology, and environmentally conscious processing technology.

The Japan Society of Applied Physics Advanced Power Semiconductors Division, The 28th Research Meeting

The Japan Society of Applied Physics Advanced Power Semiconductors Division was established to promote research and practical application of next-generation power semiconductors, which include wide-gap semiconductors such as SiC, GaN, and diamond, as well as Si-based semiconductors that play a central role in practical power devices. Researchers from a wide range of fields, including crystal growth, physical property evaluation, process technology, device development, and system applications, participate in the division to solve technical problems and promote industry-academia-government cooperation through lectures, discussion sessions, and projects to promote young researchers. They develop interdisciplinary activities that contribute to the realization of an energy-saving, low-carbon society. The 28th Research Meeting was held in SiC, GaN Machining Technology Exhibition 2025.





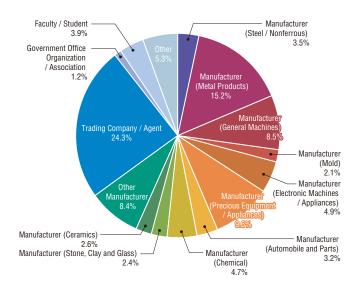




Visitors Survey

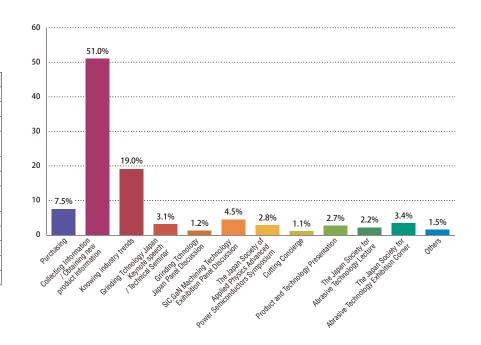
Industry Category

Industry Category	Answers
1. Manufacturer (Steel / Nonferrous)	3.5%
2. Manufacturer (Metal Products)	15.2%
3. Manufacturer (General Machines)	8.5%
4. Manufacturer (Mold)	2.1%
5. Manufacturer (Electronic Machines / Appliances)	4.9%
6. Manufacturer (Precious Equipment / Appliances)	9.6%
7. Manufacturer (Automobile and Parts)	3.2%
8. Manufacturer (Chemical)	4.7%
9. Manufacturer (Stone, Clay and Glass)	2.4%
10. Manufacturer (Ceramics)	2.6%
11. Other Manufacturer	8.4%
12. Trading Company / Agent	24.3%
13. Government Office Organization / Association	1.2%
14. Faculty / Student	3.9%
15. Other	5.3%



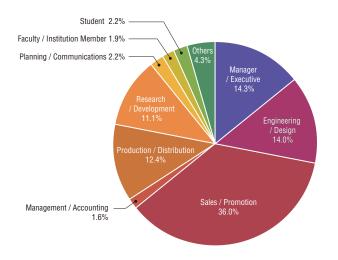
Purpose of visiting (multiple choices)

Purpose of visiting			
1. Purchasing	7.5%		
2. Collecting Information / Obtaining new product information	51.0%		
3. Knowing industry trends	19.0%		
Grinding Tchnology Japan Keynote speech Technical Seminar	3.1%		
5. Grinding Tchnology Japan Panel Discussion	1.2%		
6. SiC,GaN Machining Technology Exihibition Panel Discussion	4.5%		
7. The Japan Society of Applied Physics Advanced Power Semiconductors Symposium	2.8%		
8. Cutting Concierge	1.1%		
9. Product and Technology Presentation	2.7%		
10. The Japan Society for Abrasive Technology Lecture	2.2%		
11. The Japan Society for Abrasive Technology Exhibition Corner	3.4%		
12. Others	1.5%		



Job function

Job function	Answers
1. Manager / Executive	14.3%
2. Engineering / Design	14.0%
3. Sales / Promotion	36.0%
4. Management / Accounting	1.6%
5. Production / Distribution	12.4%
6. Research / Development	11.1%
7. Planning / Communications	2.2%
8. Faculty / Institution Member	1.9%
9. Student	2.2%
10. Others	4.3%







Visitors Survey

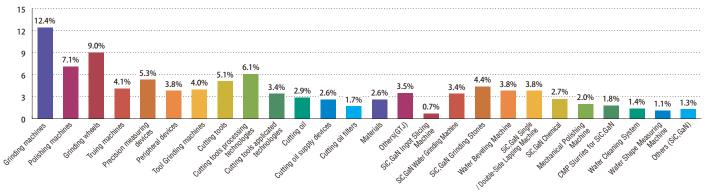
Exhibits of specific interest (multiple choices)

Grinding Technology Japan 2025

Exhibits of specific interest	Answers
1. Grinding machines	12.4%
2. Polishing machines	7.1%
3. Grinding wheels	9.0%
4. Truing machines	4.1%
Precision measuring devices	5.3%
6. Peripheral devices	3.8%
7. Tool Grinding machines	4.0%
8. Cutting tools	5.1%
Cutting tools processing technologies	6.1%

wers
11013
3.4%
2.9%
2.6%
1.7%
2.6%
3.5%
0.7%
3.4%
4.4%

Exhibits of specific interest	Answers
19. Wafer Beveling Machine	3.8%
20. SiC,GaN Single / Double-Side Lapping Machine	3.8%
21. SiC,GaN Chemical	2.7%
22. Mechanical Polishing Machine	2.0%
23. CMP Slurries for SiC,GaN	1.8%
24. Wafer Cleaning System	1.4%
25. Wafer Shape Measuring Machine	1.1%
26. Others (SiC,GaN)	1.3%

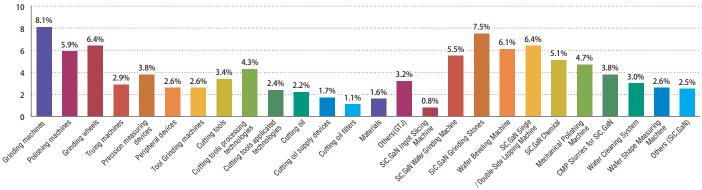


SiC, GaN Machining Technology Exhibition 2025

Exhibits of specific interest	Answers
1. Grinding machines	8.1%
2. Polishing machines	5.9%
3. Grinding wheels	6.4%
4. Truing machines	2.9%
Precision measuring devices	3.8%
6. Peripheral devices	2.6%
7. Tool Grinding machines	2.6%
8. Cutting tools	3.4%
Cutting tools processing technologies	4.3%

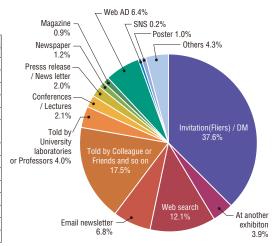
Exhibits of specific interest	Answers
10. Cutting tools applicated technologies	2.4%
11. Cutting oil	2.2%
12. Cutting oil supply devices	1.7%
13. Cutting oil filters	1.1%
14. Materials	1.6%
15. Others(GTJ)	3.2%
16. SiC,GaN Ingot Slicing Machine	0.8%
17. SiC,GaN Wafer Grinding Machine	5.5%
18. SiC,GaN Grinding Stones	7.5%

Exhibits of specific interest	Answers
19. Wafer Beveling Machine	6.1%
20. SiC,GaN Single / Double-Side Lapping Machine	6.4%
21. SiC,GaN Chemical	5.1%
22. Mechanical Polishing Machine	4.7%
23. CMP Slurries for SiC,GaN	3.8%
24. Wafer Cleaning System	3.0%
25. Wafer Shape Measuring Machine	2.6%
26. Others (SiC,GaN)	2.5%



Information SOURCE (multiple choices)

Information source about this exhibition	Answers
1. Invitation(Fliers) / DM	37.6%
2. At another exhibiton	3.9%
3. Web search	12.1%
4. Email newsletter	6.8%
5. Told by Colleague or Friends and so on	17.5%
Told by University laboratories or Professors	4.0%
7. Conferences / Lectures	2.1%
8.Presss release / News letter	2.0%
9. Newspaper	1.2%
10. Magazine	0.9%
11.Web AD	6.4%
12. SNS	0.2%
13.Poster	1.0%
14. Others	4.3%



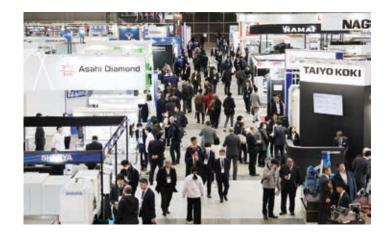
Age

Age	Answers		Less than 20 1.5%
Less than 20	1.5%		
20-29	16.1%		
30-39	20.0%	60 or more	20-29
40-49	25.2%	15.2%	16.1%
50-59	22.1%		
60 or more	15.2%		
			30 – 39 20.0%

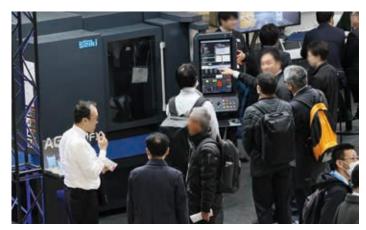




Photos of the Exhibition

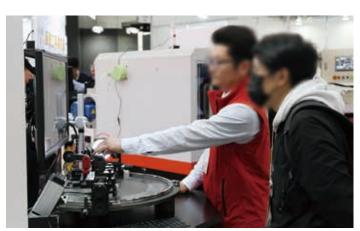














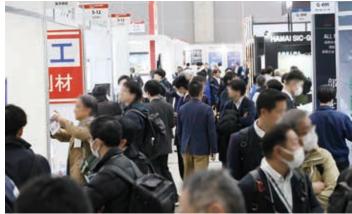


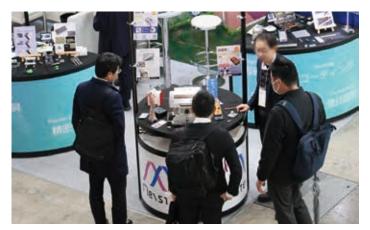


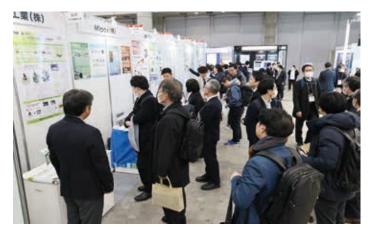


Photos of the Exhibition























2027.3.10 (Wed.) - 3.12 (Fri.)

Makuhari Messe

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